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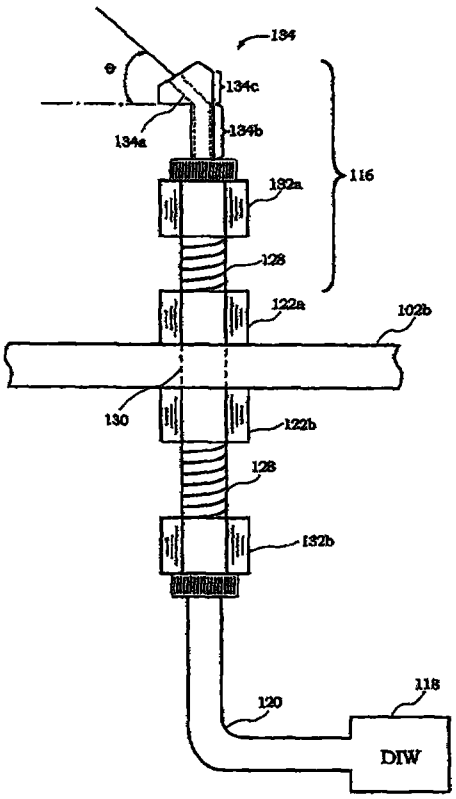
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(54) Title: SPIN, RINSE, AND DRY STATION WITH ADJUSTABLE NOZZLE ASSEMBLY FOR SEMICONDUCTOR WAFER BACKSIDE RINSING



(57) Abstract: A nozzle assembly (116) includes a connector tube (128) having a first end and a second end. An outer surface of the connector tube (128) is threaded. A first cap (132a) having an opening therethrough is threaded onto the first end of the connector tube (128). A second cap (132b) having an opening therethrough is threaded onto the second end of the connector tube (128). Each of the first and second caps has a top surface and a threaded inner surface. The nozzle assembly further includes a nozzle (134) having a tubular portion (134b) defining a channel (134a). The tubular portion (134b) is disposed in the opening of the first connector cap (132a) so that a position of the nozzle (134) can be axially and rotationally adjusted. A spin, rinse, and dry station including the adjustable nozzle assembly and a method for spin rinsing the bottom side, i.e., the backside, of a semiconductor wafer also are described.

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